

Contents 1.0 Description of Risks and Hazards

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2.0 Theory of Operation

Power levels of up to 100W and small pin-to-pin spacing make the risk of dangerous overheating quite high for USB Type-C devices and the cables used to charge them.

Environmental conditions that can lead to failure include dust, lint, water, and other liquids. Mechanical failures may lead to overcurrent events. Other mechanical failures may lead to failure. Over time, these worn-out devices can also become the source of heat, eventually leading to failure.

USB Type-C uses a configuration process over the Configuration Channel, usually referred to as the CC pin. In the USB Type-C interface (see Figure 1), this is pin A5. The configuration process is used to confirm multiple items, including:



Figure 1. USB full-featured Type-C plug interface (front view)



Figure 2. setP placement within charging system

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setP placement within charging system which causes its resistance to rise and voltage across the system to assume there is

Source: USB Type-C Cable and Connector Specification Release 1.4